

OLED DISPLAY MODULE

Product Specification

CUSTOMER	Standard	
PRODUCT NUMBER	DD-160128FC-2B	
CUSTOMER APPROVAL		Date

INTERNAL APPROVALS				
Product Mgr Doc. Control Electr. Eng				
Bruno Recaldini	Anthony Perkins	Bazile Peter		
Date: 15 Oct 10	Date: 15 Oct 10	Date: 15 Oct 10		



TABLE OF CONTENTS

I	IVL	AIN FEATURES	4
2	\mathbf{M}	ECHANICAL SPECIFICATION	5
	2.1	MECHANICAL CHARACTERISTICS	5
	2.2	MECHANICAL DRAWING	6
3	EI	LECTRICAL SPECIFICATION	7
	3.1	ABSOLUTE MAXIMUM RATINGS	7
	3.2	ELECTRICAL CHARACTERISTICS	8
	3.3	INTERFACE PIN ASSIGNMENT	
	3.4	BLOCK DIAGRAM	
	3.5	TIMING CHARACTERISTICS	
4	OI	PTICAL SPECIFICATION	18
	4.1	OPTICAL CHARACTERISTICS	18
5	FU	UNCTIONAL SPECIFICATION	19
	5.1	COMMANDS	
	5.2	POWER UP/DOWN SEQUENCE	
	5.3	RESET CIRCUIT	
	5.4	ACTUAL APPLICATION EXAMPLE	20
6	PA	ACKAGING AND LABELLING SPECIFICATION	23
7	QI	UALITY ASSURANCE SPECIFICATION	24
	7.1	CONFORMITY	24
	7.2	DELIVERY ASSURANCE	
	7.3	DEALING WITH CUSTOMER COMPLAINTS	28
8	RI	ELIABILITY SPECIFICATION	29
	8.1	RELIABILITY TESTS	29
	8.2	LIFE TIME	29
9	H	ANDLING PRECAUTIONS	30

Product No.	DD-160128FC-2B	REV. B
Floduct No.		

Page	2/30
------	------



REVISION RECORD

Rev.	Date	Page	Chapt.	Comment	ECR no.
A	22 Nov 06			First Issue	
В	26 Dec 10	4 5 7 8 18 6 11 17 19 29 4		 Overall dimensions Weight Driver Supply Voltage Operating current for VDDH Optics Characteristics Mechanical Drawing Block Diagram Add RGB interface Power up sequence Low Temperature Operation Operating temperature 	

Product No.	DD-160128FC-2B	REV. B
Product No.		

Page	3/30
------	------



1 MAIN FEATURES

ITEM	CONTENTS
Display Format	160 (RGB) x 128 Dots
Overall Dimensions	Glass 39.9 x 34.0 x 1.6 mm
Colour	262,144 Colour
Active Area	33.575 x 26.864 mm
Viewing Area	35.575 x 28.864 mm
Display Mode	Passive Matrix (1.69")
Driving Method	1/128 duty
Driver IC	SEPS525
Operating temperature	-40 ~ +70
Storage temperature	-40 ~ +80

Product No.	DD-160128FC-2B	REV. B
r toduct No.		

Dana	4./20
Page	4/30



2 MECHANICAL SPECIFICATION

2.1 MECHANICAL CHARACTERISTICS

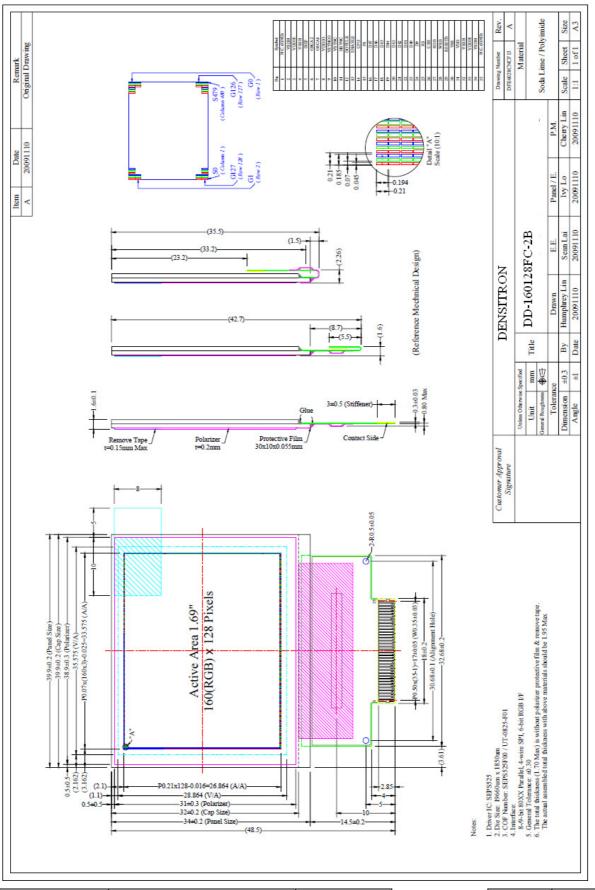
ITEM	CHARACTERISTIC	UNIT
Display Format	160 (RGB) x 128	Dots
Overall Dimensions	Glass 39.9 x 34.0 x 1.6	mm
Viewing Area	35.575 x 28.864	mm
Active Area	33.575 x 26.864	mm
Dot Size	0.045 x RGB x 0.194	mm
Dot Pitch	0.07 x RGB x 0.21	mm
Weight	4.55	g
IC Controller/Driver	SEPS525F0A (COF)	

Product No.	DD-160128FC-2B	REV. B
Floduct No.		

Page	5/30



2.2 MECHANICAL DRAWING



Product No.	DD-160128FC-2B	REV. B	Dogo	6/30
Product No.			Page	0730



3 ELECTRICAL SPECIFICATION

3.1 ABSOLUTE MAXIMUM RATINGS

VSS = 0 V, Ta = 25 °C

Item	Symbol	Min	Max	Unit	Note	
Supply Voltage	$V_{ m DD}$	-0.3	4	V		
Supply Voltage for I/O Pins	V_{DDIO}	-0.3	4	V	Note 1, 2	
Driver Supply Voltage	$V_{ m DDH}$	-0.3	16	V		
Operating Temperature	Тор	-40	70	°C		
Storage Temperature	Tst	-40	80	°C		
Static Electricity	Be sure that you are grounded when handling displays.					

Note 1: All the above voltages are on the basis of "VSS=0V".

Note 2: When this module is used beyond the above absolute maximum ratings, permanent damage to the module may occur. Also for normal operations it's desirable to use this module under the conditions according to Section 3.2 "Electrical Characteristics". If this module is used beyond these conditions the module may malfunction and the reliability could deteriorate.



3.2 ELECTRICAL CHARACTERISTICS

Characteristics	Symbol	Conditions	Min	Тур	Max	Unit
Supply Voltage	V_{DD}		2.6	2.8	3.3	V
Supply Voltage x I/O pins	$V_{ m DDIO}$		1.6	2.8	3.3	V
Driver Supply Voltage	V _{DDH}		13.5	14	14.5	V
High Level Input	V_{IH}		$0.8 \mathrm{xV}_\mathrm{DD}$	-	V_{DD}	V
Low Level Input	V _{IL}		0	-	0.4	V
High Level Output V _{OH}		$I_{OH} = -0.4 \text{mA}$	V _{DD} -0.4	-	-	V
Low Level Output	V_{OL}	$I_{OL} = -0.1 \text{mA}$	-	-	0.4	V
Operating current for VDD	Idd		-	2.5	3.5	mA
Operating current for	T	Note 1	-	26.2	32.8	A
VDDH	Iddh	Note 2	-	14.9	18.6	mA

Note 1 VDD = 2.8V, VDDH = 14V, 100% Display Area Turn On Note 2 VDD =2.8V, VDDH = 14V, 500% Display Area Turn On

Product No.	DD-160128FC-2B	REV. B
Flouuct No.		

Page	8/30
------	------



3.3 INTERFACE PIN ASSIGNMENT

Mating Connector type: 35-pin, 0.5 mm pitch FFC/FPC. Type: AVX 04-6238-035-000-800

No.	Symbol	Function
1	N.C.	Reserved Pin (Supporting Pin). The supporting pins can reduce the influences from stresses on the function pins. These pins must be connected to external ground
2	VSDH	Ground of OEL Panel These are the ground pins for analog circuits. It must be connected to external ground. VSDH: Data Driver Ground
3	VDDH	Power supply of OEL Panel This is the most positive voltage supply pin of the chip. It must be connected to external source.
4	VSSH	Ground of OEL Panel These are the ground pins for analog circuits. It must be connected to external ground. VSSH: Scan Driver Ground
5	IREF	Current reference for brightness Adjustment This pin is segment (data) current reference pin. A 68KΩ Resistor should be connected between this pin and VSS
6	OSCA2	Fine Adjustment for Oscillation
7	OSCA1	The frequency is controlled by external 5.1 kΩ Resistor between OSCA1 and OSCA2. The oscillator signal is used for system clock generation. When the external clock mode is selected, OSCA1 is used external clock input.
8	VDDIO	Power supply for Interface logic level This is a voltage supply pin. It should be match with MCU interface voltage level. It must always be equal or lower than VDD
9	VSYNCO	RGB Mode functional Pins
10	VSYNC	VSYNCO: Vertical Sync Output
11	HSYNC	VSYNC: Vertical Sync Input HSYNC: Horizontal Sync Input
12	DOTCLK	DOTCLK: Dot Clock Input
13	ENABLE	ENNABLE: Video Enable Input
14	CPU	Select CPU type Low: 80-Series High: 68-Series
15	PS	Select Parallel/Serial Interface Low: Serial High: Parallel
16	D17	Host Data Input/Output Bus.
17	D16	These pins are 9-bit bi-directional data bus to be connected with MCU data bus.
18	D15	

Product No.	DD-160128FC-2B	REV. B
Floduct No.		

Page	9/30
------	------

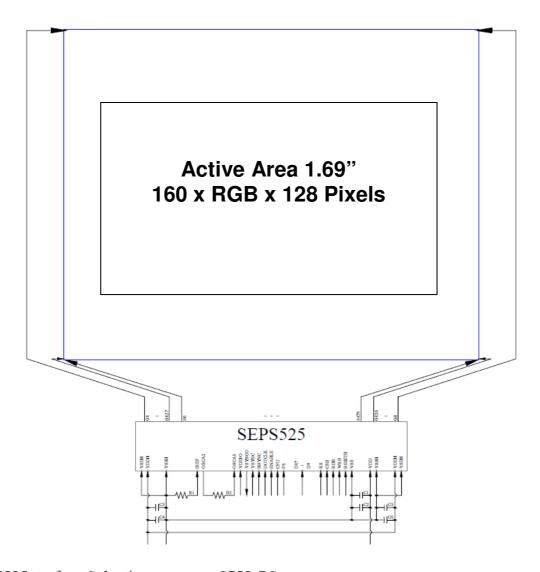


19	D14	PS	Description				
20	D13		8-bit Bus: D17 to D10				
21	D12	1	9-bit Bus: D17 to D19				
22	D11		D[17] SCL: Synchronous Clock Input				
23	D10	0	D[16] SDI: Serial Data Input D[15] SDO: Serial Data Output				
24	D9						
25	RS		Data/Command nmand High: Parameter/data				
26	CSB	Chip Sele Low: SEF					
27	RDB	80-syster 68-syster	Read/Write enable n bus interface: read strobe signal (acting bus interface: bus enable strobe (acting bus interface) n bus interface: bus enable strobe (acting bus interface)				
28	WRB	80-syster 68-syster Low: write	Read/Write select n bus interface: write strobe signal (acti n bus interface: read/write select e, High: read rial mode, fix it to VDD or VSS level	ve low)			
29	RESETB	Power Re This pin i	Power Reset for Controller and Driver This pin is reset signal input. When the pin is low, initialization of the chip is executed.				
30	VSS	Ground of Logic Circuit A reference for the logic pins. It must be connected to external ground					
31	VDD		pply for logic circuit voltage supply pin. It must be connected	d to external			
32	VSSH	These are connecte	of OEL Panel the ground pins for analog circuits. It indicated to the differential different dif	must be			
33	VDDH	This is the	pply of OEL Panel e most positive voltage supply pin of the e connected to external source.	e chip.			
34	VSDH	These are connecte	of OEL Panel the ground pins for analog circuits. It in to external ground. ata Driver Ground	must be			
35	NC	The supp	I Pin (Supporting Pin). Porting pins can reduce the influences fraction pins. These pins must be connectioned				

Droduct No.	DD-160128FC-2B	REV. B	Dogo	10 / 30
Product No.			Page	10 / 30



3.4 BLOCK DIAGRAM



MCU Interface Selection: CPU, PS

Pins connected to MCU interface: D17~D9, RS, CSB, RDB, WRB, and RESETB Pins connected to RGB interface: D17~D12, VSYNC, HSYNC, DOTCLK, and

ENABLE

C1, C3, C5: 0.1μF C2: 4.7μF

C4, C6: 4.7µF / 25V Tantalum Capacitor

R1: $68k\Omega$ R2: $5.1k\Omega$

Product No.	DD-160128FC-2B	REV. B
Floduct No.		

Page	11/30
------	-------



3.5 TIMING CHARACTERISTICS

3.5.1 AC CHARACTERISTICS

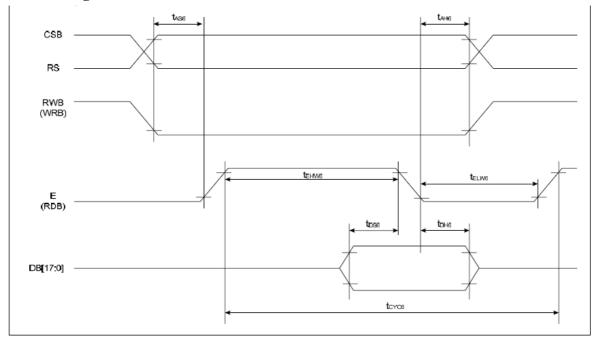
3.5.1.1 6800-Series MPU Parallel Interface Timing Characteristics

VDD = 2.8V, Ta = 25°C

Characteristics	Symbol	Min	Max	Unit	Port
Write Timing					
Address hold timing	tAH6	5		nS	CSB
Address setup timing	tAS6	5	-	113	RS
System cycle timing Write	tCYC6	100			
"L" pulse width Write	tELW6	45	-	nS	Е
"H" pulse width	tEHW6	45			
Data setup timing	tDS6	40		~ C	DD[17.0]
Data hold timing	tDH6	10	1 -	nS	DB[17:0]
Read Timing					
Address hold timing	tAH6	10		nS	CSB
Address setup timing	tAS6	10	_	113	RS
System cycle timing Write	tCYC6	200			
"L" pulse width Write	tELW6	90] -	nS	Е
"H" pulse width	tEHW6	90			
Data setup timing (CL= 15pF)	tDS6	0	70	nS	DB[17:0]
Data hold timing (CL= 15pF)	tDH6	U	70	110	[0.71]טע

• All the timing should be based on 10% and 90% of V_{DD} .

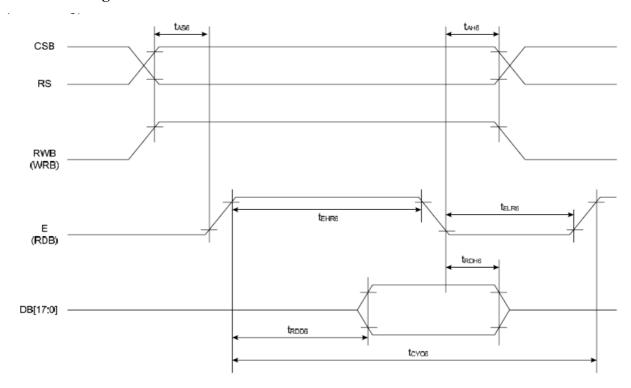
Write Timing



Droduct No.	DD-160128FC-2B	REV. B	Dogo	12/30
Product No.			Page	12 / 30



Read Timing



Product No.	DD-160128FC-2B	REV. B
Floduct No.		

Page	13 / 30
------	---------

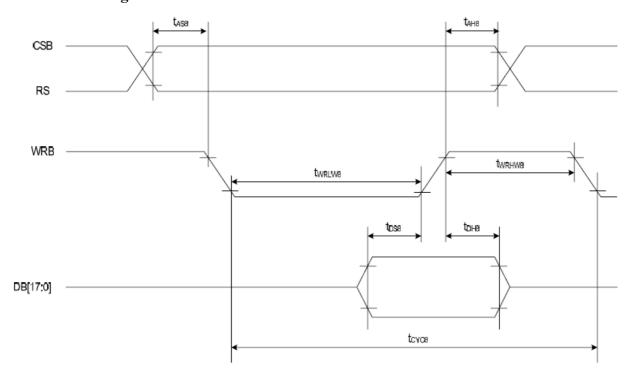


3.5.1.2 8080-Series MPU Parallel Interface Timing Characteristics

Characteristics	Symbol	Min	Max	Unit	Port
Write Timing					
Address hold timing	tAH8	5		nS	CSB
Address setup timing	tAS8	5	-	113	RS
System cycle timing Write	tCYC8	100			
"L" pulse width Write	tELW8	45] -	nS	WRB
"H" pulse width	tEHW8	45			
Data setup timing	tDS8	30		C	DD[17.0]
Data hold timing	tDH8	10	-	nS	DB[17:0]
Read Timing					
Address hold timing	tAH8	10		nS	CSB
Address setup timing	tAS8	10] -	113	RS
System cycle timing Write	tCYC8	200			
"L" pulse width Write	tELW8	90] -	nS	RDB
"H" pulse width	tEHW8	90			
Data setup timing (CL= 15pF)	tDS8	0	60	nS	DB[17:0]
Data hold timing (CL= 15pF)	tDH8	U	00	113	[0.71]מע

^{*} All the timing should be based on 10% and 90% of $\emph{V}_{\textrm{DD}}$

Write Timing

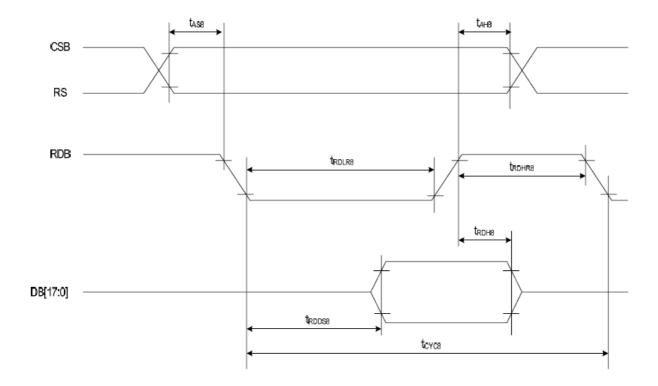


Product No.	DD-160128FC-2B	REV. B	
Floduct No.			

Page	14/30
------	-------



Read timing



Product No.	DD-160128FC-2B	REV. B
Floduct No.		

Page	15/30
------	-------



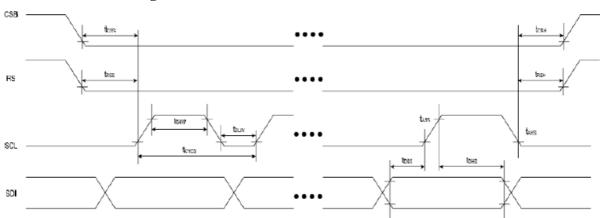
3.5.1.3 Serial Interface Timing Characteristics

VDD = 2.8V, Ta = 25°C

					,
ITEM	SYMBOL	MIN	MAX	UNIT	PORT
Serial clock cycle SCL	tCYCS	60			
"H" pulse width SCL	tSHW	25	-	nS	SCL
"L" pulse width	tSLW	25			
Data setup timing Data	tDSS	25		nS	SDI
Hold timing	tDHS	25	-	113	SDI
CSB-SCL timing	tCSS	25		C	CCD
CSB-hold timing	tCSH	25	1	nS	CSB

* All the timing should be based on 10% and 90% of $\emph{V}_{\textrm{DD}}$

Serial Interface Timing



Product No.	DD-160128FC-2B	REV. B
Floduct No.		

Page	16/30

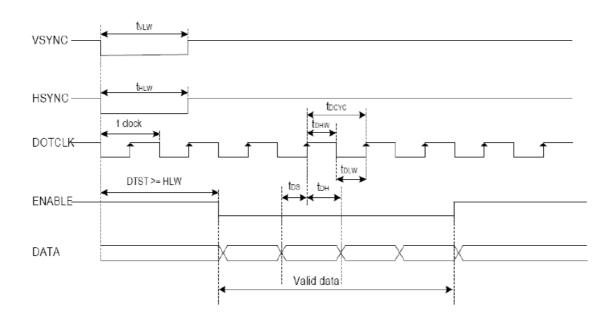


3.5.1.4 RGB Interface Timing Characteristics:

 $(V_{DD} = 2.8V, T_a = 25^{\circ}C)$

Symbol	Item	Min	Max	Unit	Port
t _{DCYC}	Dot Clock Cycle	100	-	ns	
t_{DLW}	Dot "L" Pulse Width	50	-	ns	DOTCLK
t_{DHW}	Dot "H" Pulse Width	50	-	ns	
t _{DS}	Data Setup Timing	5	-	ns	D[17.12]
t _{DH}	Data Hold Timing	5	-	ns	D[17:12]
$t_{\rm VLW}$	Vsync Pulse Width	1	-	DOTCLK	VSYNC
t _{HLW}	Hsync Pulse Width	1	-	DOTCLK	HSYNC

^{*} All the timing reference is 10% and 90% of V_{DD} .



DTST: Setup Time for Data Transmission

* VSYNC, HSYNC, ENABLE, and D[17:12] should be transmitted by 3 clocks for one pixel (RGB).

Product No.	DD-160128FC-2B	REV. B
Floduct No.		

Page	17/30



4 OPTICAL SPECIFICATION

4.1 OPTICAL CHARACTERISTICS

Characteristics	Symbol	Condition	Min	Тур	Max	Unit
Brightness(White)	L_{br}	Note 1	60	75	-	cd/m ²
C LE (White)	(X)	CIE 1021	0.26	0.30	0.34	-
C.I.E.(White)	(Y)	C.I.E. 1931	0.29	0.33	0.37	
C.I.E.(Red)	(X)	CIE 1021	0.60	0.64	0.68	
C.I.E.(Red)	(Y)	C.I.E. 1931	0.30	0.34	0.38	-
C.I.E.(Green)	(X)	C.I.E. 1931	0.27	0.31	0.35	
C.I.E.(Gleen)	(Y)	C.I.E. 1931	0.58	0.62	0.66	-
C.I.E.(Blue)	(X)	C.I.E. 1931	0.10	0.14	0.18	
C.I.E.(Diue)	(Y)	C.I.E. 1931	0.12	0.16	0.20	-
Dark Room Contrast	CR		-	>2000:1	-	-
Viewing Angle			>160	-	-	degree

Note 1: Brightness (Lbr) and Supply Voltage for Display (VDDH) are subject to the change of the panel characteristics and the customer's request.

Optical measurement with polarizer is taken at VDD, VDDIO = 2.8V, VDDH = 14V and the software initial setting with section 5.4.1 Reference parameter table for normal operation mode.

Product No.	DD-160128FC-2B	REV. B
Floduct No.		

Page	18 / 30
------	---------



5 FUNCTIONAL SPECIFICATION

5.1 COMMANDS

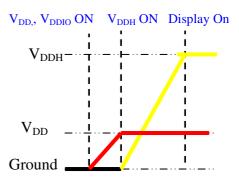
Please refer to the Technical Manual for the SEPS525

5.2 POWER UP/DOWN SEQUENCE

To protect panel and extend the panel lifetime, the driver IC power up/down routine should include a delay period between high voltage and low voltage power sources during turn on/off. It gives the panel enough time to complete the action of charge and discharge before/after the operation.

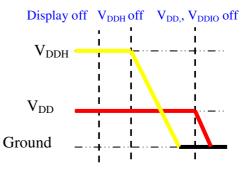
5.2.1 POWER UP SEQUENCE

- 1. Power up $V_{DD\,\&}$ $V_{DD\,IO}$
- 2. Send Display off command
- 3. Initialization
- 4. Clear Screen
- 5. Power up V_{DDH}
- 6. Delay 100ms (When V_{DD} & V_{DDIO} is stable)
- 7. Send Display on command



5.2.2 POWER DOWN SEQUENCE

- 1. Send Display off command
- 2. Power down V_{DDH}
- 3. Delay 100ms (When V_{DDH} reach 0 and panel is completely discharges)
- 4. Power down V_{DD} & V_{DDIO}



5.3 RESET CIRCUIT

When RESETB input is low, the chip is initialized with the following status:

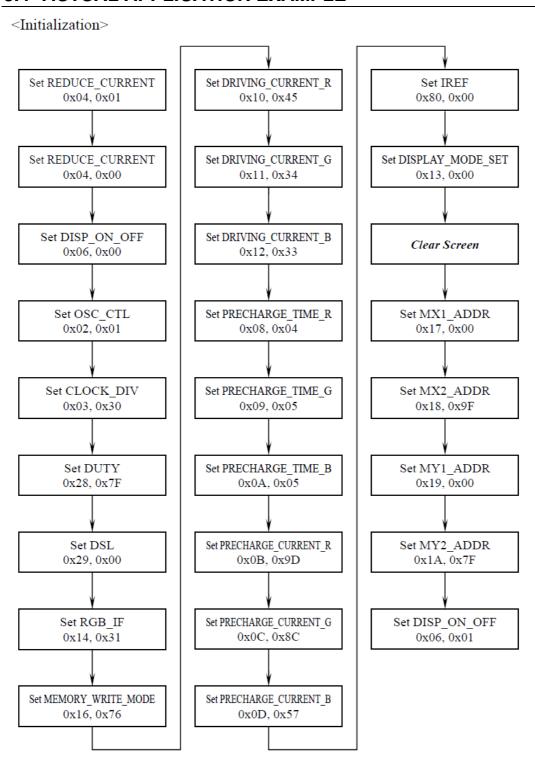
- 1. Frame frequency: 90Hz
- 2. OSC: internal OSC
- 3. Internal OSC: ON
- 4. DDRAM write horizontal address: MX1 = 00h, MX2 = 9Fh
- 5. DDRAM write vertical address: MY1 = 00h, MY2 = 7Fh
- 6. Display data RAM write: HC = 1, VC = 1, HV = 0
- 7. RGB data swap: OFF
- 8. Row scan shift direction: G0, G1, ..., G126, G127
- 9. Column data shift direction: S0, S1, ..., S478, S479
- 10. Display ON/OFF: OFF
- 11. Panel display size: FX1 = 00h, FX2 = 9Fh, FY1 = 00h, FY2 = 7Fh
- 12. Display data RAM read column/row address: FAC = 00h, FAR = 00h
- 13. Pre-charge time(R/G/B): 0 clock
- 14. Pre-charge current(R/G/B): 0 uA 15. Driving current(R/G/B): 0 uA

Product No.	DD-160128FC-2B	REV. B
Floduct No.		

Page	19 / 30
------	---------



5.4 ACTUAL APPLICATION EXAMPLE



If the noise is accidentally occurred at the displaying window during the operation, please reset the display in order to recover the display function.

Product No.	DD-160128FC-2B	REV. B	Dogo	20 / 30
Floduct No.			Page	20730



5.4.1 Reference Parameters Table

 $(VDD = 2.8V, Ta = 25^{\circ}C)$

Command Parameter	Normal operation mode	Power saving mode	
Set Display On_Off	0x06, 0x00		
Set SOFT_RST	0x05, 0x00		
Set REDUCE _CURRENT	0x04, 0x01 wait 1ms 0x04,0x00		
Set OSC_CTL	0x02, 0	0x01	
Set CLOCK_DIV	0x03, 0	0x09	
Set PRECHARGE_TIME_R	0x08, 0x03	0x08, 0x00	
Set PRECHARGE_TIME_G	0x09, 0x05	0x09, 0x00	
Set PRECHARGE_TIME_B	0x0A, 0x05	0x0A, 0x00	
Set PRECHARGE_CURRENT_R	0x0B, 0x56	0x0B, 0x00	
Set PRECHARGE_CURRENT_G	0x0C, 0x4D	0x0C, 0x00	
Set PRECHARGE_CURRENT_B	0x0D, 0x46	0x0D, 0x00	
Set DRIVING_CURRENT_R	0x10, 0x0A	0x10, 0x0D	
Set DRIVING_CURRENT_G	0x11, 0x0A	0x11, 0x0C	
Set DRIVING_CURRENT_B	0x12, 0x0A	0x12, 0x0B	
Set DISPLAY_MODE_SET	0x13, 0x00		
Set RGB_IF	0x14, 0x01		
Set RGB_POL	0x15, 0x00		
Set MEMORY_WRITE_MODE	0x16, 0x76		
Set MX1_ADDR	0x17, 0	0x00	
Set MX2_ADDR	0x18, 0	x9F	
Set MY1_ADDR	0x19, 0	0x00	
Set MY2_ADDR	0x1A, 0)x7F	
Set MEMORY_ACCESS_POINTER X	0x20, 0x00		
Set MEMORY_ACCESS_POINTER Y	0x21, 0x00		
Set DUTY	0x28, 0x7F		
Set DSL	0x29, 0x00		
Set D1_DDRAM_FAC	0x2E, 0x00		
Set D1_DDRAM_FAR	0x2F, 0x00		

Product No.	DD-160128FC-2B	REV. B
Product No.		

Page	21/30
------	-------

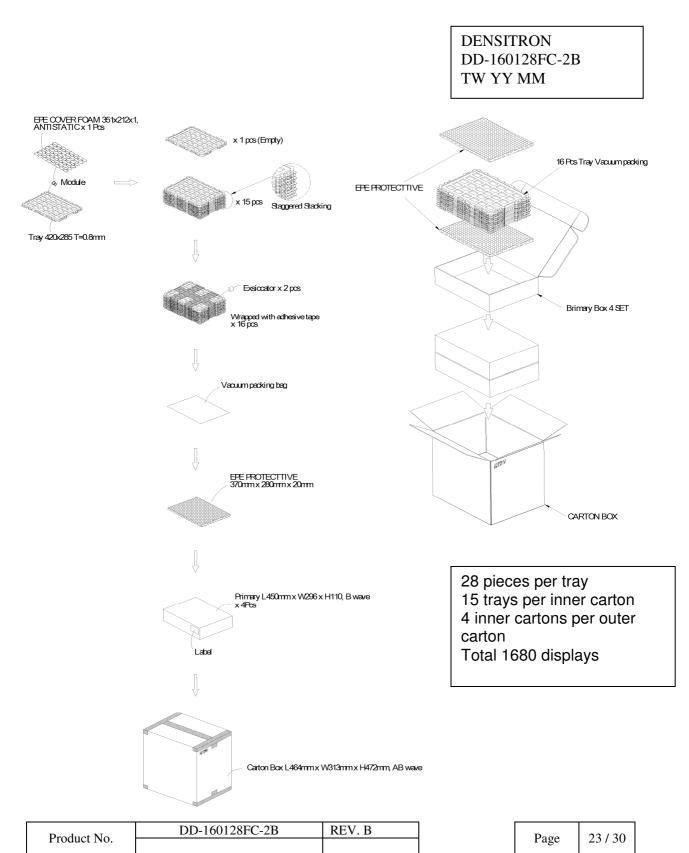


Set D1_DDRAM_SAC	0x31, 0x00
Set D1_DDRAM_SAR	0x32, 0x00
Set SCR1_FX1	0x33, 0x00
Set SCR1_FX2	0x34, 0x9F
Set SCR1_FY1	0x35, 0x00
Set SCR1_FY2	0x36, 0x7F
Set IREF	0x80, 0x00
Set DISP_ON_OFF	0x06, 0x01

Product No.	DD-160128FC-2B	REV. B
Flouuct No.		

Page	22 / 30
------	---------

6 PACKAGING AND LABELLING SPECIFICATION





7 QUALITY ASSURANCE SPECIFICATION

7.1 CONFORMITY

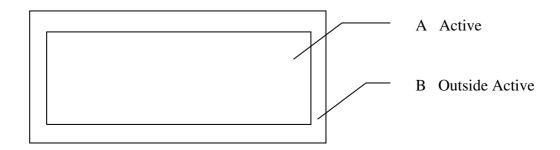
The performance, function and reliability of the shipped products conform to the Product Specification.

7.2 DELIVERY ASSURANCE

7.2.1 DELIVERY INSPECTION STANDARDS

IPC-AA610, class 2 electronic assemblies standard

7.2.2 Zone definition



7.2.3 Visual inspection

Test and measurement to be conducted under following conditions:

Distance between the Panel & the lamp:

Temperature: 23 ± 5 °C Humidity: $55\pm15\%$ RH Fluorescent lamp: 30 W Distance between the Panel & Eyes of the Inspector: $\geqq 30 \text{ cm}$

Product No.	DD-160128FC-2B	REV. B
Floduct No.		

Page	24 / 30
------	---------

≥50cm



7.2.4 Standard of appearance inspection

Units: mm

Class	Item			Criteria	1	
Minor	Packing &	Outside & ir	nside package	Presence of pro	oduct no., lot no.,	quantity
Critical	Label			d with others and		<u> </u>
			d on the label			
Major	Dimension	Product dim	ensions must	be according to sp	pecification and di	rawing
Major	Electrical	Product elec	trical charact	eristics must be ac	ecording to specifi	cation
Critical	OLED Display	Missing line allowed	s, short circui	its or wrong patter	ns on OLED disp	lay are not
Minor	Black spot, white spot,	Round type: $\emptyset = (X+Y)/2$	as per follow	ving drawing		
	dust			A	cceptable quantity	/
				Size	Zone A	Zone B
			<u> </u>	Ø<0.1	Any number	
			Y	0.1<Ø<0.2	3	1
		1	F	0.2<Ø<0.25	1	Any number
		X		0.25<Ø	0	
		Line type: as per following drawing Acceptable quantity				
		W	Length	Width	Zone A	Zone B
		~ */*		W≤0.05	Any number	
			L≤2.0	W≤0.1	3	Any number
			L>2.0		0	
		L	Total accept	table quantity: 3		
Minor	Polariser	Scratch on p	rotective film	is permitted		
	scratch	Scratch on polariser: same as No. 1				
Minor	Polariser	$\emptyset = (X+Y)/2$	2			
	bubble	Acceptable quantity				
				Size	Zone A	Zone B
			<u> </u>	Ø<0.5	Any number	Any number
		X	Y	Ø>0.5	0	

Product No.	DD-160128FC-2B	REV. B
Flouuct No.		

Page 25 / 30



Class	Item	Criteria		
Minor	Segment deformation	1b. Pin hole on dot matrix display	Acceptable Size $a,b<0.1$ $(a+b)/2\leq0.1$ $0.5<\emptyset<1.0$ Total acceptable	Any number Any number 3
		2. Segments / dots with different width	Accep a≥b a <b< td=""><td>table a/b≤4/3 a/b>4/3</td></b<>	table a/b≤4/3 a/b>4/3
		3. Alignment layer defect $\emptyset = (a+b)/2$	Acceptable Size $\emptyset \le 0.4$ $0.4 < \emptyset \le 1.0$ $1.0 < \emptyset \le 1.5$ $1.5 < \emptyset \le 2.0$ Total acceptable	Any number 5 3 2
Minor	Panel Chipping	$X \le 1/6$ Panel length $Y \le 1$ $Z \le T$		7
Minor	Panel Cracking	Cracks not allowed		
Minor	Cupper exposed (pin or film)	Not allowed if visible by eye inspection		
Minor	Film or Trace Damage	Not allowed if affect electrical function		

Product No.	DD-160128FC-2B	REV. B
Floduct No.		



Class	Item	Criteria			
Minor	Contact Lead Twist	Not allowed		D. TVISTED LEAD	
Minor	Contact Lead Broken	Not allowed		A. BROKEN LEAD	
Minor	Contact Lead Bent	Not allowed if bent lead causes short circuit			
		Not allowed if bent extends horizontall more than 50% of its width	/		
Minor	Colour uniformity	Level of sample for approval set as limit sample			
Major	PCB _	No unmelted solder paste should be present on PCB			
Critical		Cold solder joints, missing solder connections, or oxidation are not allowed			
Minor		No residue or solder balls on PCB are allowed			
Critical		Short circuits on components are not allowed			
Minor	Tray particles	Size Quantity $\emptyset < 0.2$ Any number		Quantity Any number	
	particles		On tray	Ø<0.2 Ø>0.25	4
			On 411	Ø≥0.25	2
			On display	L = 3	1

Product No.	DD-160128FC-2B	REV. B
Product No.		

Page	27 / 30
rage	21130



7.3 DEALING WITH CUSTOMER COMPLAINTS

7.3.1 Non-conforming analysis

Purchaser should supply Densitron with detailed data of non-conforming sample. After accepting it, Densitron should complete the analysis in two weeks from receiving the sample.

If the analysis cannot be completed on time, Densitron must inform the purchaser.

7.3.2 Handling of non-conforming displays

If any non-conforming displays are found during customer acceptance inspection which Densitron is clearly responsible for, return them to Densitron.

Both Densitron and customer should analyse the reason and discuss the handling of non-conforming displays when the reason is not clear.

Equally, both sides should discuss and come to agreement for issues pertaining to modification of Densitron quality assurance standard.

Product No.	DD-160128FC-2B	REV. B
Floduct No.		

Page	28 / 30
------	---------



8 RELIABILITY SPECIFICATION

8.1 RELIABILITY TESTS

Test Item	Test Condition	Evaluation and assessment	
High Temperature Operation	70°C±2, 240 hours	No abnormalities in function and appearance	
Low Temperature Operation	-40°C±2, 240 hours	No abnormalities in function and appearance	
High Temperature Storage	80°C±2, 240 hours	No abnormalities in function and appearance	
Low Temperature Storage	-40°C±2, 240 hours	No abnormalities in function and appearance	
High Temperature & High Humidity Storage(Operation)	60°C±2, 90%RH, 120 hours	No abnormalities in function and appearance	
Thermal Shock	24 cycle of -40°C 1 Hour, 85°C 1 Hour	No abnormalities in function and appearance	

- The brightness should be greater than 50% of the initial brightness.
- The samples used for above tests do not include polarizer.
- No moisture condensation is observed during tests.

8.1.1 FAILURE CHECK STANDARD

After the completion of the described reliability test, the samples were left at room temperature for 2 hrs prior to conducting the failure teat at 23±5 °C; 55±15% RH

8.2 LIFE TIME

Item	Description
1	Function, performance, appearance, etc. shall be free from remarkable deterioration more than 10,000 hours under 75 cd/m² brightness and storage conditions of room temperature (25±10 °C), normal humidity (45±20% RH), and in area not exposed to direct sunlight.
2	End of lifetime is specified as 50% of initial brightness.

Droduct No	DD-160128FC-2B	REV. B
Product No.		

Page	29 / 30
------	---------



9 HANDLING PRECAUTIONS

Safety

If the panel breaks, be careful not to get the organic substance in your mouth or in your eyes. If the organic substance touches your skin or clothes, wash it off immediately using soap and plenty of water.

Mounting and Design

Place a transparent plate (e.g. acrylic, polycarbonate or glass) on the display surface to protect the display from external pressure. Leave a small gap between the transparent plate and the display surface.

Design the system so that no input signal is given unless the power supply voltage is applied.

Caution during OLED cleaning

Lightly wipe the display surface with a soft cloth soaked with Isopropyl alcohol, Ethyl alcohol or Trichlorotriflorothane.

Do not wipe the display surface with dry or hard materials that will damage the polariser surface. Do not use aromatic solvents (toluene and xylene), or ketonic solvents (ketone and acetone).

Caution against static charge

As the display uses C-MOS LSI drivers, connect any unused input terminal to V_{DD} or V_{SS} . Do not input any signals before power is turned on.

Also, ground your body, work/assembly table and assembly equipment to protect against static electricity.

Packaging

Displays use OLED elements, and must be treated as such. Avoid strong shock and drop from a height.

To prevent displays from degradation, do not operate or store them exposed directly to sunshine or high temperature/humidity.

Caution during operation

It is indispensable to drive the display within the specified voltage limit since excessive voltage shortens its life.

Other Precautions

When a display module is operated for a long of time with fixed pattern may remain as an after image or slight contrast deviation may occur.

Nonetheless, if the operation is interrupted and left unused for a while, normal state can be restored. Also, there will be no problem in the reliability of the module.

Storage

Store the display in a dark place where the temperature is $25^{\circ}\text{C} \pm 10^{\circ}\text{C}$ and the humidity below 50%RH

Store the display in a clean environment, free from dust, organic solvents and corrosive gases. Do not crash, shake or jolt the display (including accessories).

Product No.	DD-160128FC-2B	REV. B
Product No.		

Page	30 / 30
------	---------